

# **Connector Datasheet**

## PT06M00004R1 Micro SIM H1.5 WITH TRAY PUSH PUSH TYPE H=1.5mm

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Version	Changed Reason		Changed by	Date
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## TECHNICAL INFORMATION

### MATERIALS

• Materials used in the construction of product shall be as specified on the applicable product drawing

## ELECTRICAL PERFORMANCE

Voltage Rating : 10V DC

Current Rating : 0.5Amps Max

Contact Resistance (signal) :  $100m \Omega$  Initial ( $140m \Omega$  After Test) Max.

Insulation Resistance : 500M  $\Omega$  Min. at 500VDC.

Dielectric Withstanding Voltage : 250VAC/Minute .

Operating Temperature : -25° C~+85° C

## MECHANICAL PERFORMANCE

- Card Insertion Force : Initial value:1.0Kg Max.
- Card Release Force : Initial value: 0.1Kgf Max.
- Contact Retention Force : Male: 300gf / pin Min.
- Durability : 5000 cycles

## PACKING

Reel packing



#### TEST REQUIREMENTS AND PROCEDURES SUMMARY

Test Description	Requirement	PROCEDURED	
Examination of product	Meets requirements of product drawing and Specification.	Visual inspection No physical damage	
Electrical			
	Connector contacts:		
	Initial: 100mΩ max	$\sim$	
Low Level	After test: 140mΩ max	Mate dummy card, measure by dry circuit, 20mV max,10mA max. (EIA 364- 23)	
Contact	R 40mΩ max		
Resistance	Detection switch contact		
	Initial: 500mΩ max		
	After test:540mΩ max	C. Y	
Insulation Resistance	1000MΩ Min. at 500V DC / 2min.	EIA-364-21-E	
Dielectric Withstanding Voltage	No breakdown at 500V RMS	ЕІА-364-20-Е	
MECHANICAL			
	5000 time	Insertion and extraction are	
	Appearance: No damage	repeated 7000 cycles with the actually card at the speed rate of	
Durability	contact.Resistance:150mΩMax.	400~600 cycles/hour. Exchange the	
	Measuring by dummy card	actually card every 2000 cycles (EIA364-09)	
Card Insertion Force	Initial value:1.0Kg Max.	Speed 25±3mm/minute	
Card Release Force	Initial value: 1.0Kgf Max.	Speed 25±3mm/minute	
Vibration	Appearance: no damage. Discontinuity: 1 microsecond Max.	Mate dummy card and place them on the vibrator, then apply the following vibration. Then it shall be measured. In accordance with EIA- 364-28 Frequency :10Hz→55Hz→ 10Hz.	
		Direction :Three mutually perpendicular directions.	
A Y		Total amplitude : 1.50mm	
0,,		Sweep duration : 2 hours for each direction, a total of 6 hours.	
Mechanical Shock	Appearance: no damage. Discontinuity: 1 microsecond Max.	Mate dummy card and place them on the vibrator, then apply the following vibration. Then it shall be measured. In accordance with EIA- 364-28 Frequency :10Hz→55Hz→ 10Hz.	
		Direction : Three mutually perpendicular directions.	



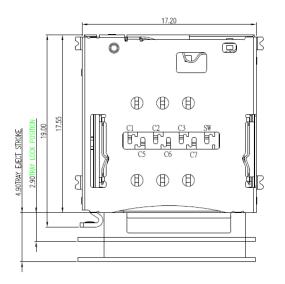
		Sweep duration : 2 hours for each direction, a total of 6 hours.
ENVIRONMENTAL		
Humidity	Meets requirements of product drawing and electrical specification.	EIA-364-31C method II Condition A
Salt spray	Meets requirements of product drawing and electrical specification.	Mate dummy card and expose them to the following environment in accordance with EIA-364-26. Temperature : $35 \pm 2^{\circ}C$ Relative Humidity: $95 \sim 98\%$ RH Salt water density: $5+/-1\%$ (by weight) Duration : 24 hours
Low Temperature	Meets requirements of product drawing and electrical specification	The connector housing shall be store at temperature of -25 ± 3°C for 48hours
Dry heat	Meets requirements of product drawing and electrical specification	The connector housing shall be store at temperature of 85 ± 2°C for 96hours EIA-364-17C
Thermal Cycling	No abnormality	Cycle the connector between -15°C +/-3 °C and 85°C+/-3°C. Ramps should be 1 °C min. per minute, and dwell times should ensure the contacts reach the temperature extremes (5 minutes min.). Humidity is not controlled. Perform 100 such cycles. Follow EIA-364-110
Solderability	The test area shall be covered more than 95% of immersed area with flash solder	Solder Temperature: $240 ^{\circ}\text{C} \pm 5 ^{\circ}\text{C}$ Immersion Period: $3 \pm 0.5$ sec.
Resistance to Soldering Heat	<ol> <li>Without deformation of case or excessive loosen.</li> <li>Electrical characteristics shall be satisfied</li> </ol>	Place the connector on the P.C. Board, then immerse the solder pin up to the surface of the board in the solder bath at $260^{\circ}C \pm 5^{\circ}C$ for 5 sec.(Included $245^{\circ}C \pm 5^{\circ}C$ for 10 sec.)

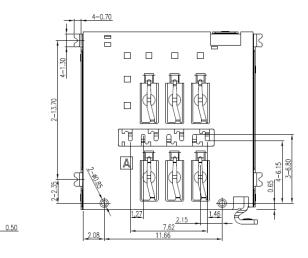
Figure 1

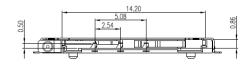
NOTE: Shall meet visual requirements, show no physical damages.



## **Component Configuration and Dimensions**









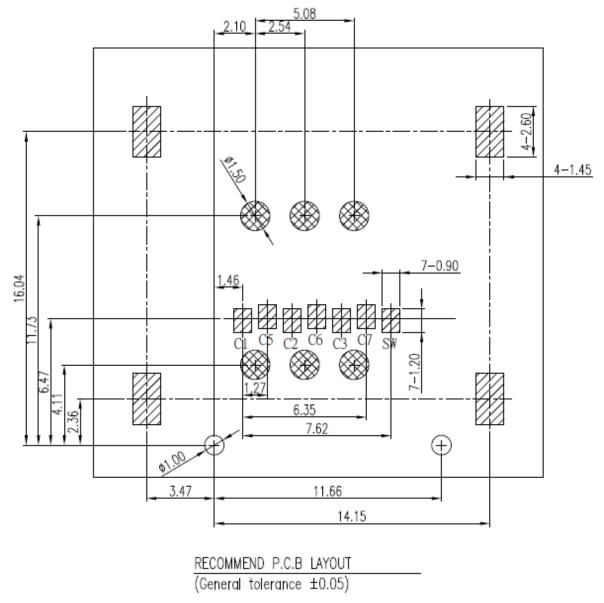


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## Pins assignment for PCB Layout

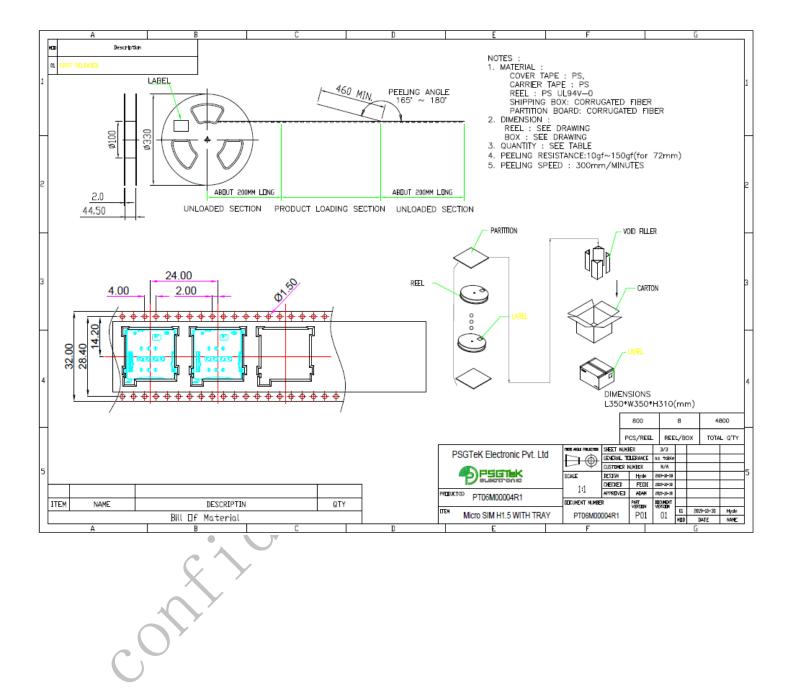


NO trace

NO trace,NO test point NO via hole,NO ground area

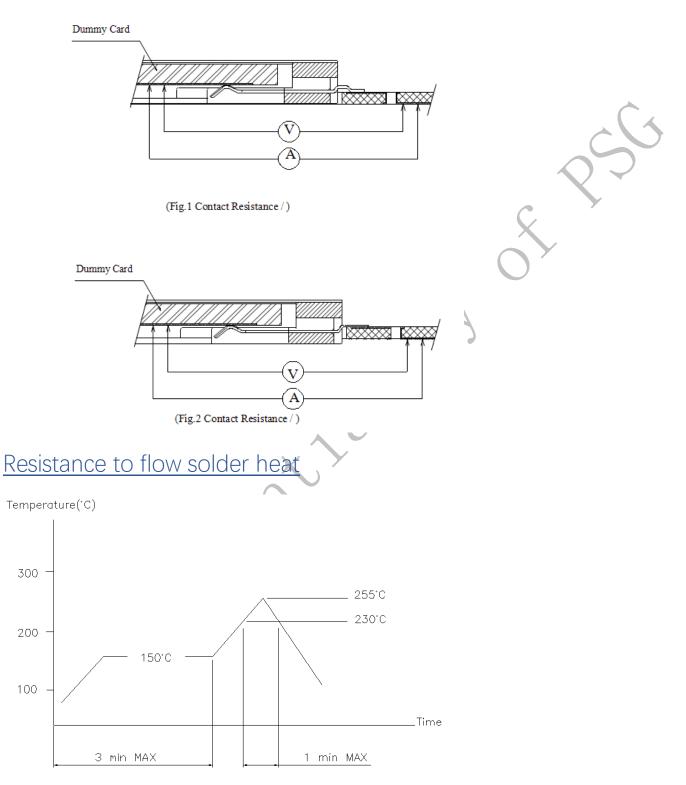


## Packing drawing





## Contact Resistance



Note: The product specification only for standard product